



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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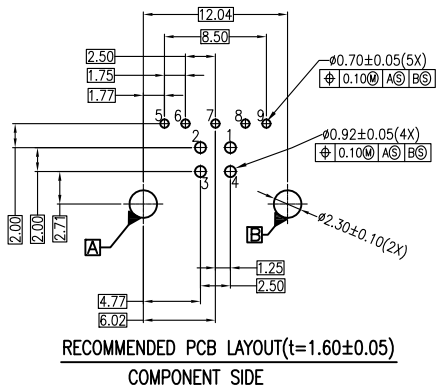
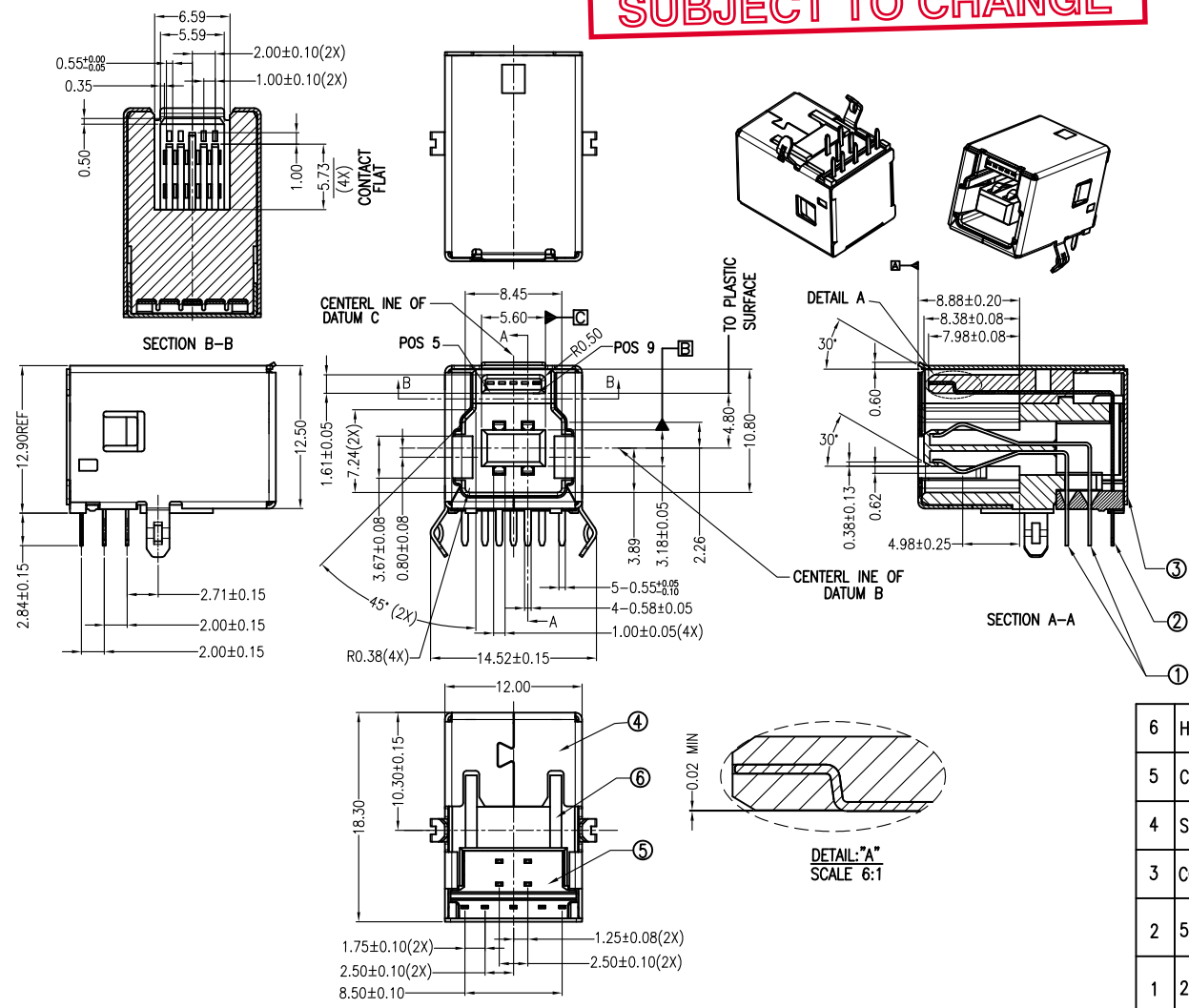


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The marking on this product doesn't contain environmental hazardous materials per Material Specification 55-00259 for Sony GP compliant or per directive 2002/95/EC for RoHS compliant.

**PRELIMINARY RELEASE
SUBJECT TO CHANGE**

| REVISIONS | | | | |
|-----------|---------|---------------------|------------|-----------|
| SYM | ECN No. | DESCRIPTION | DATE | APPROVED |
| AX1 | | UNAPPROVED REVISION | 06/03/2009 | Arron Lin |
| AX2 | | MODIFIED MATERIAL | 06/19/2009 | Arron Lin |
| AX3 | | MODIFIED NOTES | 07/29/2009 | Arron Lin |
| AX4 | | MODIFIED NOTES | 09/25/2009 | Arron Lin |
| AX5 | | MODIFIED PN No. | 11/12/2009 | Arron Lin |



| ITEM | DESC. | MATERIAL | REMARKS | PART REMARKS |
|------|-------------|-----------------------------|---|--------------|
| 6 | HOUSING | LCP | 30%GF UL94V-0 COLOR:BLUE 300C | |
| 5 | COVER | LCP | 30%GF UL94V-0 COLOR:BLUE 300C | |
| 4 | SHELL | BRASS (T=0.30mm) | OVER-PLATING:NI 30u" | |
| 3 | COVER SHELL | SPCC T=0.30 | OVER-PLATING:NI 80u" | |
| 2 | 5P TERMINAL | BRASS (T=0.20mm) | UNDER-PLATING:NI 30u" SOLDER AREA:Sn 120u" CONTACT AREA:GOLD 30u" | |
| 1 | 2P TERMINAL | PHOSPHOR BRONZE T=0.25mm | UNDER-PLATING:NI 30u" SOLDER AREA:Sn 120u" CONTACT AREA:GOLD 30u" | |

| TOLERANCE | DRAWN | APPROVALS | DATE | TITLE | Amphenol® | | | |
|----------------------------|----------|--------------|--------------------|--|---|----------|-------------|----------|
| X. | DESIGNED | Daniel Hsieh | 09/25/2009 | USB 3.0 B TYPE CONNECTOR R/A DIP TYPE | Amphenol Corporation Amphenol Taiwan Corporation | | | |
| X.X ±0.30 | CHECKED | Roger Tsai | 09/25/2009 | | | | | |
| X.XX ±0.20 | APPROVED | Arron Lin | 09/25/2009 | UNIT mm SCALE NA | SIZE A3 | PART No. | GSB321131HR | |
| X.XXX ±0.10 | DWG TYPE | CUST DWG | PROJECT CODE OTHER | | SHEET 1 OF 1 | DWG No. | GSB321131HR | REV. AX5 |
| ANGULAR ±1° | | | | | | | | |
| UNLESS OTHERWISE SPECIFIED | | | | | | | | |